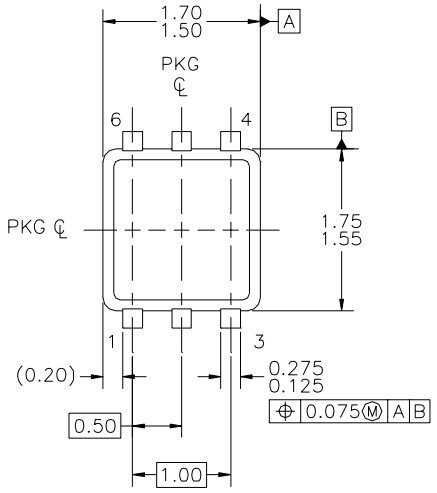
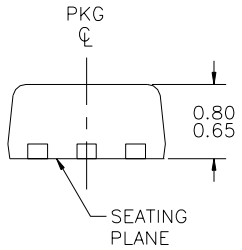
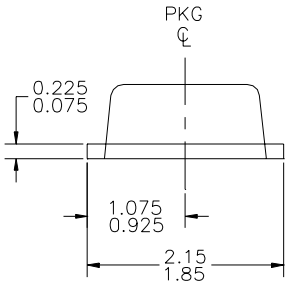
SC75-6 Bottomless Package Dimensions

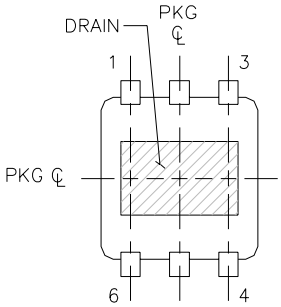
FAIRCHILD SEMICONDUCTOR®

SC75-6 Bottomless









BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

A) NO PACKAGE STANDARD REFERENCE AS OF JULY 13, 2000.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
D) LEAD TIP BURR:
HORIZONTAL: 0.10 mm MAX
VERTICAL UP: 0.10 mm MAX
VERTICAL DOWN: 0.05 mm MAX

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